

10/042,408

L Number	Hits	Search Text	DB	Time stamp
5	669	((((ball adj grid) BGA PGA (pin adj grid)) and @ad<19940318) and wire) and (encapsula\$5 epoxy resin packag\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/29 12:52
6	81	(((((ball adj grid) BGA PGA (pin adj grid)) and @ad<19940318) and wire) and (encapsula\$5 epoxy resin packag\$3)) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/29 12:47
7	140	((ball adj grid) BGA PGA (pin adj grid)) and @ad<19940318 and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/29 13:13
8	103	(substrate near8 pattern\$3) and @ad<19940318 and (BGA PGA)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/29 13:15
9	146	((metal\$8 wir\$3) near8 pattern\$3) and @ad<19940318 and (BGA PGA)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/29 13:23
10	0	((metal\$8 wir\$3) near8 (repeat\$4 adj pattern\$3)) and @ad<19940318 and (BGA PGA)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/29 13:24
11	100	((metal\$8 wir\$3) near8 (repeat\$4 adj pattern\$3)) and @ad<19940318	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/29 13:25
12	34	((metal\$8 wir\$3) near8 (repeat\$4 adj pattern\$3)) and @ad<19940318) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/29 14:05
13	4	((("5729894") or ("5578869")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/29 14:06
-	3828	((ball adj grid) BGA PGA (pin adj grid)) and @ad<19940318	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/29 10:55
-	844	((ball adj grid) BGA PGA (pin adj grid)) and @ad<19940318) and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/29 10:55
-	669	(((((ball adj grid) BGA PGA (pin adj grid)) and @ad<19940318) and wire) and (encapsula\$5 epoxy resin packag\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/29 12:46